

mos integrated circuit $\mu PD16638A$

300/309 OUTPUT TFT-LCD SOURCE DRIVER (COMPATIBLE WITH 64 GRAY SCALES)

The μ PD16638A is a source driver for TFT-LCDs capable of dealing with displays with 64 gray scales. Data input is based on digital input configured as 6 bits by 3 dots (1 pixels), which can realize a full-color display of 260,000 colors by output of 64 values γ -corrected by an internal D/A converter and 9-by-2 external power modules. Because the output dynamic range is as large as 8.3 V_{P-P}, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion, n-line inversion and column line inversion when mounted on a single side, this source driver is equipped with a built-in 6-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a maximum clock frequency of 40 MHz when driving at 3.0 V, this driver is applicable to SVGA and XGA-standard TFT-LCD panels.

FEATURES

- Capable of outputting 64 values by means of 9-by-2 external power modules (18 units) and a D/A converter
- Output dynamic range 8.3 V_{p-p} min. (@ V_{DD2} = 8.5 V)
- · CMOS level input
- Input of 6 bits (gradation data) by 3 dots
- High-speed data transfer: fmax. = 40 MHz (internal data transfer speed when operating at 3.0 V)
- Apply for dot-line inversion, n-line inversion and column line inversion
- Number of output is selectable (300/309)
- Single bank arrangement is possible (loaded with slim or bending TCP)

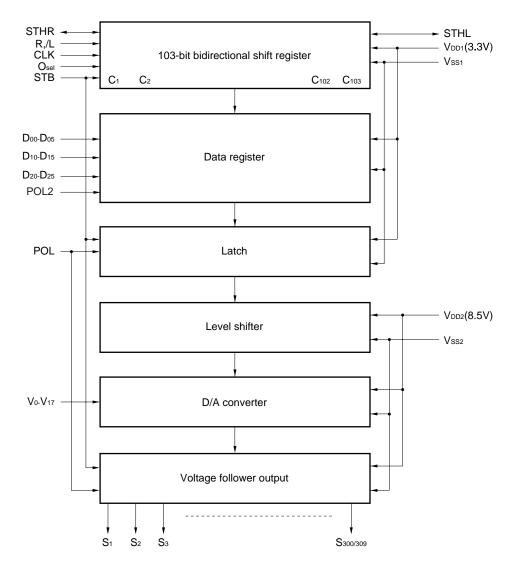
ORDERING INFORMATION

Part Number	Package
μPD16638AN-×××	TCP (TAB package)

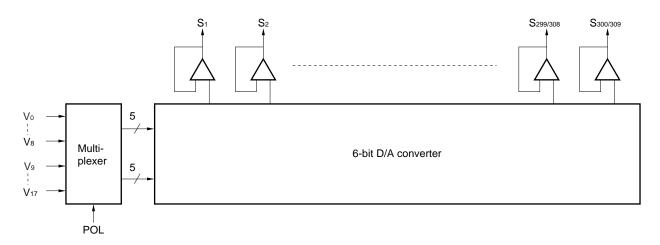
The TCP's external shape is customized. To order your TCP's external shape, please contact a NEC salesperson.

The information contained in this document is being issued in advance of the production cycle for the device. The parameters for the device may change before final production or NEC Corporation, at its own discretion, may withdraw the device prior to its production.

BLOCK DIAGRAM

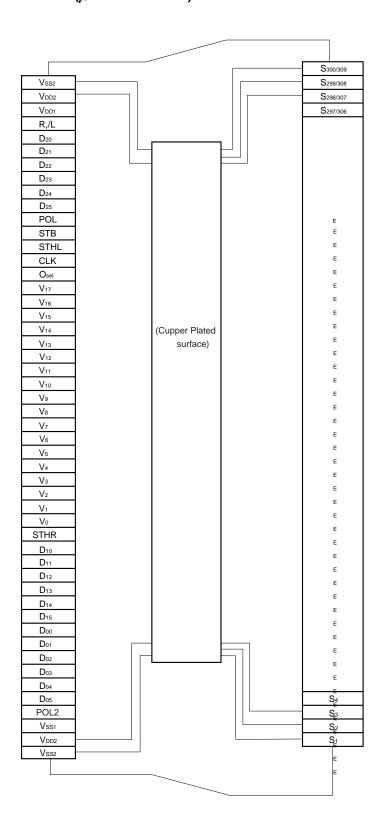


RELATIONSHIP BETWEEN OUTPUT CIRCUIT AND D/A CONVERTER





PIN CONFIGURATION (μPD16638AN-xxx)



Remark This figure does not specify the TCP package. LPC terminal is pulled up to the VDD1 in the chip.



1. PIN FUNCTIONS

Pin Symbol	Pin Name	Description
S ₁ to S _{300/309}	Driver output	The D/A converted 64-gray-scale analog voltage is output.
D ₀₁ to D ₀₅	Display data input	The display data is input with a width of 18 bits, viz., the gray scale data (6 bits)
D ₁₀ to D ₁₅		by 3 dots (1 pixels).
D ₂₀ to D ₂₅		Dxo: LSB, Dxs: MSB
R,/L	Shift direction control input	These refer to the start pulse input/output pins when driver ICs are connected in cascade. The shift directions of the shift registers are as follows. R,/L = H: STHR input, S ₁ \rightarrow S _{300/309} , STHL output R,/L = L: STHL input, S _{300/309} \rightarrow S ₁ , STHR output
STHR	Right shift start pulse input/output	R,/L = H: Becomes the start pulse input pin. R,/L = L: Becomes the start pulse output pin.
STHL	Left shift start pulse input/output	R,/L = H: Becomes the start pulse output pin. R,/L = L: Becomes the start pulse input pin.
Osel	Number of output pins select pin	This pin selects the number of output pins. $O_{sel} = H$: 300-output mode $O_{sel} = L$: 309-output mode
CLK	Shift clock input	Refers to the shift register's shift clock input. The display data is incorporated into the data register at the rising edge. $O_{\text{sel}} = \text{H: At the rising edge of the 100th clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver. O_{\text{sel}} = \text{L: At the rising edge of the 103rd clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver.}$
STB	Latch input	The contents of the data register are transferred to the latch circuit at the rising edge. And, at the falling edge, the gray scale voltage is supplied to the driver. It is necessary to ensure input of one pulse per horizontal period.
POL	Polarity input	POL = H: The S_{2n-1} output uses V_0 to V_8 as the reference supply. The S_{2n} output uses V_9 to V_{17} as the reference supply. POL = L: The S_{2n-1} output uses V_0 to V_8 as the reference supply. The S_{2n} output uses V_0 to V_8 as the reference supply. S_{2n-1} indicates the odd output: and S_{2n} indicates the even output. Input of the POL signal is allowed the setup time(tpol-stb) with respect to STB's rising edge.
POL2	Data inversion	POL2 = H: Display data is inverted. POL2 = L: Display data is not inverted.
Vo to V ₁₇	γ -corrected power supplies	Input the γ -corrected power supplies from outside by using operational amplifier. Make sure to maintain the following relationships. During the gray scale voltage output, be sure to keep the gray scale level power supply at a constant level. $V_{DD2} > V_0 > V_1 > V_2 > V_3 > V_4 > V_5 > V_6 > V_7 > V_8 > V_9 > V_{10} > V_{11} > V_{12} > V_{13} > V_{14} > V_{15} > V_{16} > V_{17} > V_{SS2}$
V _{DD1}	Test pin Logic power supply	3.3 V ±0.3 V
V _{DD2}	Driver power supply	8.0 V to 9.0 V
Vss1	Logic ground	Grounding
Vss2	Driver ground	Grounding

- Cautions 1. The power start sequence must be V_{DD1}, logic input, and V_{DD2} & V₀ to V₁₇ in that order. Reverse this sequence to shut down. (Simultaneous power application to V_{DD2} and V₀ to V₁₇ is possible.)
 - 2. To stabilize the supply voltage, please be sure to insert a 0.1 μ F bypass capacitor between V_{DD1} - V_{SS1} and V_{DD2} - V_{SS2} . Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about 0.01 μ F is also advised between the γ -corrected power supply terminals (V_0 , V_1 , V_2 , ..., V_{17}) and V_{SS2} .

2. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

This product incorporates a 6-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode (common electrode) voltage. The D/A converter consists of ladder resistors and switches.

Figure 2–1 shows the relationship between the driving voltages such as liquid-crystal driving voltages V_{DD2} and V_{SS2} , common electrode potential V_{COM} , and γ -corrected voltages V_0 to V_{17} and the input data. Be sure to maintain the voltage relationships of

 $V_{DD2} > V_0 > V_1 > V_2 > V_3 > V_4 > V_5 > V_6 > V_7 > V_8 > V_{COM} > V_9 > V_{10} > V_{11} > V_{12} > V_{13} > V_{14} > V_{15} > V_{16} > V_{17} > V_{SS2}.$

Figures 2–2 and 2–3 show the relationship between the input data and the output data. This driver IC is designed for only single-sided mounting. Therefore, please do not use it for γ -corrected power supply level inversion in double-sided mounting. Because the current flowing through ladder resistors r_0 to r_{62} is small, its use for double-sided mounting impairs the IC's stable operation when the level of the γ -corrected power supply terminal is inverted thus causing display failures. And please input γ -corrected power supply voltage by using operational amplifier to keep driver output accuracy.

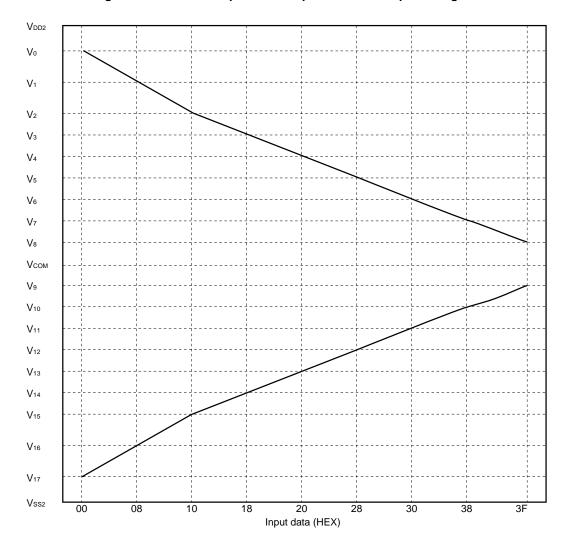


Figure 2-1. Relationship between Input Data and Output Voltage

ro

r₁

r2 **r**3

r4

r5

r6

r7

r₈ **r**9

r10

r11 **r**12 **r**13

r14 **r**15 **r**16

r17 **r**18 **r**19

r20 **r**21

r22

r23

r24 **r**25

r26 **r**27 **r**28

r29

r30

r31

r32

r33

r34 **r**35

r36

r37

r38 **r**39

r40 **r**41

r42

r43 **r**44

r45

r46 **r**47

r48

r49 **r**50

r51

r52 **r**53

r54

r55

r56

r57

r58 **r**59

r61

r62

r63 rtotal 20000

 (Ω) 500

500

500

500 500

500

500

500

250 250

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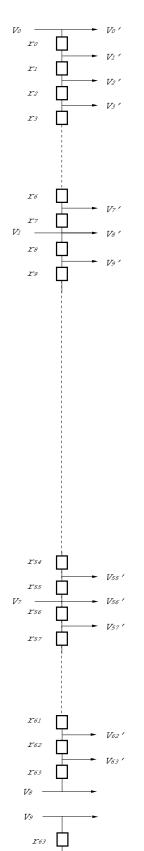
500

500 500

500 500 500

500

Figure 2-2. Relationship between Input Data and Output Voltage(1/2) $V_{DD2} > V_0 > V_1 > V_2 > V_3 > V_4 > V_5 > V_6 > V_7 > V_8$



Data	D _{X5}	D _{X4}	Dxз	D _{X2}	D _{X1}	Dxo		Output Voltage
00н	0	0	0	0	0	0	Vo'	V ₀
01н	0	0	0	0	0	1	V ₁ '	V ₁ +(V ₀ -V ₁)×3500/4000
02н	0	0	0	0	1	0	V2'	V1+(V0-V1)×3000/4000
03н	0	0	0	0	1	1	V3'	V ₁ +(V ₀ -V ₁)×2500/4000
04н	0	0	0	1	0	0	V ₄ '	V ₁ +(V ₀ -V ₁)×2000/4000
05н	0	0	0	1	0	1	V ₅ '	V ₁ +(V ₀ -V ₁)×1500/4000
06н	0	0	0	1	1	0	V ₅	V ₁ +(V ₀ -V ₁)×1000/4000
00н	0	0	0	1	1	1	V ₆	V ₁ +(V ₀ -V ₁)×1000/4000 V ₁ +(V ₀ -V ₁)×500/4000
								,
08н	0	0	1	0	0	0	V8'	V ₁
09н	0	0	1	0	0	1	V9'	V ₂ +(V ₁ -V ₂)×1750/2000
0Ан	0	0	1	0	1	0	V ₁₀ '	V ₂ +(V ₁ -V ₂)×1500/2000
0Вн	0	0	1	0	1	1	V ₁₁ '	V ₂ +(V ₁ -V ₂)×1250/2000
0Сн	0	0	1	1	0	0	V ₁₂ '	V ₂ +(V ₁ -V ₂)×1000/2000
0DH	0	0	1	1	0	1	V13'	V2+(V1-V2)×750/2000
0Ен	0	0	1	1	1	0	V ₁₄ '	V ₂ +(V ₁ -V ₂)×500/2000
0Fн	0	0	1	1	1	1	V ₁₅ '	V ₂ +(V ₁ -V ₂)×250/2000
10н	0	1	0	0	0	0	V ₁₆ '	V_2
11н	0	1	0	0	0	1	V ₁₇ '	V ₃ +(V ₂ -V ₃)×1750/2000
12н	0	1	0	0	1	0	V ₁₈ '	V ₃ +(V ₂ -V ₃)×1500/2000
13н	0	1	0	0	1	1	V ₁₉ '	V ₃ +(V ₂ -V ₃)×1250/2000
14 _H	0	1	0	1	0	0	V ₂₀ '	V ₃ +(V ₂ -V ₃)×1000/2000
15н	0	1	0	1	0	1	V ₂₁ '	V ₃ +(V ₂ -V ₃)×750/2000
16н	0	1	0	1	1	0	V22'	V ₃ +(V ₂ -V ₃)×500/2000
17 _H	0	1	0	1	1	1	V22'	V ₃ +(V ₂ -V ₃)×250/2000
18H	0	1	1	0	0	0	V23	V3+(V2-V3)/230/2000 V3
	0	1	1	0		1		V ₄ +(V ₃ -V ₄)×1750/2000
19 _H					0		V ₂₅ '	(
1A _H	0	1	1	0	1	0	V ₂₆ '	V ₄ +(V ₃ -V ₄)×1500/2000
1B _H	0	1	1	0	1	1	V27'	V4+(V3-V4)×1250/2000
1C _H	0	1	1	1	0	0	V ₂₈ '	V ₄ +(V ₃ -V ₄)×1000/2000
1Dн	0	1	1	1	0	1	V ₂₉ '	V ₄ +(V ₃ -V ₄)×750/2000
1Ен	0	1	1	1	1	0	V30'	V ₄ +(V ₃ -V ₄)×500/2000
1Fн	0	1	1	1	1	1	V31'	V ₄ +(V ₃ -V ₄)×250/2000
20н	1	0	0	0	0	0	V32'	V ₄
21н	1	0	0	0	0	1	V33'	V ₅ +(V ₄ -V ₅)×1750/2000
22н	1	0	0	0	1	0	V ₃₄ '	V ₅ +(V ₄ -V ₅)×1500/2000
23н	1	0	0	0	1	1	V35'	V ₅ +(V ₄ -V ₅)×1250/2000
24н	1	0	0	1	0	0	V36'	V ₅ +(V ₄ -V ₅)×1000/2000
25н	1	0	0	1	0	1	V ₃₇ '	V ₅ +(V ₄ -V ₅)×750/2000
26н	1	0	0	1	1	0	V38'	V5+(V4-V5)×500/2000
27н	1	0	0	1	1	1	V ₃₉ '	V ₅ +(V ₄ -V ₅)×250/2000
28н	1	0	1	0	0	0	V ₄₀ '	V ₅
29н	1	0	1	0	0	1	V ₄₁ '	V ₆ +(V ₅ -V ₆)×1750/2000
2Ан	1	0	1	0	1	0	V41'	V ₆ +(V ₅ -V ₆)×1500/2000
2Вн	1	0	1	0	1	1	V ₄₂ '	V ₆ +(V ₅ -V ₆)×1250/2000
2CH	1	0	1	1	0	0	V43	V ₆ +(V ₅ -V ₆)×1000/2000
2Dн	1	0	1	1	0	1	V ₄₄	V ₆ +(V ₅ -V ₆)×750/2000
2Бн 2Ен								,
	1	0	1	1	1	0 1	V46'	V ₆ +(V ₅ -V ₆)×500/2000
2F _H			•	_	•	_	V ₄₇ '	V ₆ +(V ₅ -V ₆)×250/2000
30н	1	1	0	0	0	0	V48'	V ₆
31н	1	1	0	0	0	1	V49'	V7+(V6-V7)×1750/2000
32н	1	1	0	0	1	0	V ₅₀ '	V ₇ +(V ₆ -V ₇)×1500/2000
33н	1	1	0	0	1	1	V ₅₁ '	V ₇ +(V ₆ -V ₇)×1250/2000
34н	1	1	0	1	0	0	V52'	V7+(V6-V7)×1000/2000
35н	1	1	0	1	0	1	V ₅₃ '	V ₇ +(V ₆ -V ₇)×750/2000
36н	1	1	0	1	1	0	V ₅₄ '	V7+(V6-V7)×500/2000
37н	1	1	0	1	1	1	V ₅₅ '	V7+(V6-V7)×250/2000
38н	1	1	1	0	0	0	V ₅₆ '	V ₇
39н	1	1	1	0	0	1	V ₅₇ '	V ₈ +(V ₇ -V ₈)×3500/4000
3Ан	1	1	1	0	1	0	V ₅₈ '	V ₈ +(V ₇ -V ₈)×3000/4000
	1	1	1	0	1	1	V 58	V ₈ +(V ₇ -V ₈)×3500/4000
38⊬ □					0	0	V ₆₀ '	
3Bн 3C⊔	1	1						
3Сн	1	1	1	1				V ₈ +(V ₇ -V ₈)×2000/4000
	1 1 1	1 1	1	1	0	1	V ₆₀ V ₆₁ ' V ₆₂ '	V ₈ +(V ₇ -V ₈)×2000/4000 V ₈ +(V ₇ -V ₈)×1500/4000 V ₈ +(V ₇ -V ₈)×1000/4000

Caution Between V₈ and V₉ terminal is not connected in the chip.

Figure 2–3. Relationship between Input Data and Output Voltage(2/2) $V_9 > V_{10} > V_{11} > V_{12} > V_{13} > V_{14} > V_{15} > V_{16} > V_{17} > V_{SS2}$

		Data	D _{X5}	D _{X4}	Dx3	D _{X2}	D _{X1}	Dxo	Output Voltage		(Ω)
L 62	□ ŀ	3 Fн	1	1	1	1	1	1	V ₆₃ " V ₁₀ +(V ₉ -V ₁₀)×3500/4000	r 63	500
	₩ V63 '	<u> 3Ен</u>	1	1	1	1	1	0	V ₆₃ V ₁₀ +(V ₉ -V ₁₀)×3000/4000 V ₆₂ " V ₁₀ +(V ₉ -V ₁₀)×3000/4000	r ₆₂	500
L 63	T I	3DH	1	1	1	1	0	1	V ₆₁ " V ₁₀ +(V ₉ -V ₁₀)×2500/4000	r 61	500
V8 -	┸→ ╽	3Сн	1	1	1	1	0	0	V ₆₀ " V ₁₀ +(V ₉ -V ₁₀)×2000/4000	r 60	500
		3Вн	1	1	1	0	1	1	V ₅₉ " V ₁₀ +(V ₉ -V ₁₀)×1500/4000	r 59	500
_		3Ан	1	1	1	0	1	0	V ₅₈ " V ₁₀ +(V ₉ -V ₁₀)×1000/4000	r 58	500
V9 1°63	一	39н	1	1	1	0	0	1	V ₅₇ " V ₁₀ +(V ₉ -V ₁₀)×500/4000	r 57	500
	V ₆₃ ′′	38н 37н	1	1	0	0 1	0	0	V ₅₆ " V ₁₀ V ₅₅ " V ₁₁ +(V ₁₀ -V ₁₁)×1750/2000	r 56	500 250
Ľ62		36н	1	1	0	1	1	0	V ₅₄ " V ₁₁ +(V ₁₀ -V ₁₁)×1500/2000	r 54	250
	V62''	35н	1	1	0	1	0	1	V ₅₃ " V ₁₁ +(V ₁₀ -V ₁₁)×1250/2000	r 53	250
L 61		34н	1	1	0	1	0	0	V ₅₂ " V ₁₁ +(V ₁₀ -V ₁₁)×1000/2000	r 52	250
101	V61 ''	33н	1	1	0	0	1	1	V ₅₁ " V ₁₁ +(V ₁₀ -V ₁₁)×750/2000	r 51	250
1 60		32H	1	1	0	0	1	0	V ₅₀ " V ₁₁ +(V ₁₀ -V ₁₁)×500/2000	r 50	250
	T	31н 30н	1	1	0	0	0	0	V49" V11+(V10-V11)×250/2000 V48" V11	r ₄₉	250 250
	l l	2Fн	1	0	1	1	1	1	V48 V11 V47" V12+(V11-V12)×1750/2000	r ₄₇	250
	.	<u> 2</u> Ен	1	0	1	1	1	0	V ₄₆ " V ₁₂ +(V ₁₁ -V ₁₂)×1500/2000	r 46	250
		2Dн	1	0	1	1	0	1	V ₄₅ " V ₁₂ +(V ₁₁ -V ₁₂)×1250/2000	r 45	250
rce.	<u> </u>	2Сн	1	0	1	1	0	0	V44" V12+(V11-V12)×1000/2000	r 44	250
Y 57	V57''	2Вн	1	0	1	0	1	1	V ₄₃ " V ₁₂ +(V ₁₁ -V ₁₂)×750/2000	r 43	250
¥56		2Ан 29н	1	0	1	0	0	0	V ₄₂ " V ₁₂ +(V ₁₁ -V ₁₂)×500/2000 V ₄₁ " V ₁₂ +(V ₁₁ -V ₁₂)×250/2000	r 42	250 250
V10 —	V56''	<u> 29н</u> 28н	1	0	1	0	0	0	V41 V12+(V11-V12)×230/2000 V40" V12	r ₄₁	250
£55	\Box	27н	1	0	0	1	1	1	V ₃₉ " V ₁₃ +(V ₁₂ -V ₁₃)×1750/2000	r 39	250
	V55′′	26н	1	0	0	1	1	0	V ₃₈ " V ₁₃ +(V ₁₂ -V ₁₃)×1500/2000	r 38	250
¥54	LJ [25н	1	0	0	1	0	1	V ₃₇ " V ₁₃ +(V ₁₂ -V ₁₃)×1250/2000	r 37	250
		24н	1	0	0	1	0	0	V36" V13+(V12-V13)×1000/2000	r 36	250
		23н	1	0	0	0	1	1	V ₃₅ " V ₁₃ +(V ₁₂ -V ₁₃)×750/2000	r 35	250
		22н 21н	1	0	0	0	0	0 1	V ₃₄ " V ₁₃ +(V ₁₂ -V ₁₃)×500/2000 V ₃₃ " V ₁₃ +(V ₁₂ -V ₁₃)×250/2000	r 34	250 250
	<u> </u>	20H	1	0	0	0	0	0	V ₃₃ V ₁₃ +(V ₁₂ -V ₁₃)×250/2000	r 33	250
	-	1F _H	0	1	1	1	1	1	V ₃₁ " V ₁₄ +(V ₁₃ -V ₁₄)×1750/2000	r 31	250
		1Ен	0	1	1	1	1	0	V ₃₀ " V ₁₄ +(V ₁₃ -V ₁₄)×1500/2000	r 30	250
		1Dн	0	1	1	1	0	1	V ₂₉ " V ₁₄ +(V ₁₃ -V ₁₄)×1250/2000	r 29	250
		1C _H	0	1	1	1	0	0	V ₂₈ " V ₁₄ +(V ₁₃ -V ₁₄)×1000/2000	r 28	250
	-	1B _H	0	1	1	0	1	1	V ₂₇ " V ₁₄ +(V ₁₃ -V ₁₄)×750/2000	r 27	250
	<u> </u>	1Ан 19н	0	1	1	0	0	0 1	V ₂₆ " V ₁₄ +(V ₁₃ -V ₁₄)×500/2000 V ₂₅ " V ₁₄ +(V ₁₃ -V ₁₄)×250/2000	r 26	250 250
	 	18H	0	1	1	0	0	0	V25 V14+(V15-V14)×230/2000	r ₂₄	250
	<u> </u>	17 _H	0	1	0	1	1	1	V ₂₃ " V ₁₅ +(V ₁₄ -V ₁₅)×1750/2000	r 23	250
	_	16н	0	1	0	1	1	0	V ₂₂ " V ₁₅ +(V ₁₄ -V ₁₅)×1500/2000	r 22	250
		15н	0	1	0	1	0	1	V ₂₁ " V ₁₅ +(V ₁₄ -V ₁₅)×1250/2000	r 21	250
	į	14н	0	1	0	1	0	0	V ₂₀ " V ₁₅ +(V ₁₄ -V ₁₅)×1000/2000	r 20	250
200	<u> </u>	13н	0	1	0	0	1	1	V ₁₉ " V ₁₅ +(V ₁₄ -V ₁₅)×750/2000	r 19	250
1 '9	Ŭ <i>V∘′′</i>	<u>12н</u> 11н	0	1	0	0	0	0	V ₁₈ " V ₁₅ +(V ₁₄ -V ₁₅)×500/2000 V ₁₇ " V ₁₅ +(V ₁₄ -V ₁₅)×250/2000	r 18	250 250
Ľ8		10 _H	0	1	0	0	0	0	V16" V15+(V14+V15)×230/2000	r 16	250
V16 —	₩ V8''	0 F н	0	0	1	1	1	1	V ₁₅ " V ₁₆ +(V ₁₅ -V ₁₆)×1750/2000	r 15	250
1 77	T I	0Ен	0	0	1	1	1	0	V14" V16+(V15-V16)×1500/2000	r 14	250
	V7′′	0Dн	0	0	1	1	0	1	V ₁₃ " V ₁₆ +(V ₁₅ -V ₁₆)×1250/2000	r 13	250
L 6	LJ L	0Сн	0	0	1	1	0	0	V ₁₂ " V ₁₆ +(V ₁₅ -V ₁₆)×1000/2000	r 12	250
	i .	0Вн	0	0	1	0	1	1	V11" V16+(V15-V16)×750/2000 V10" V16+(V15-V16)×500/2000	r 11	250
		0Ан 09н	0	0	1	0	0	0 1	V9" V16+(V15-V16)×300/2000	r 10	250 250
		08н	0	0	1	0	0	0	V8" V16	r ₈	250
		07н	0	0	0	1	1	1	V7" V17+(V16-V17)×3500/4000	r 7	500
		06н	0	0	0	1	1	0	V6" V17+(V16-V17)×3000/4000	r 6	500
	[05н	0	0	0	1	0	1	V5" V17+(V16-V17)×2500/4000	r 5	500
Ľ2		04н 03н	0	0	0	0	<u>0</u>	<u>0</u>	V ₄ " V ₁₇ +(V ₁₆ -V ₁₇)×2000/4000 V ₃ " V ₁₇ +(V ₁₆ -V ₁₇)×1500/4000	r ₄	500 500
		03н 02н	0	0	0	0	1	0	V ₃ V ₁₇ +(V ₁₆ -V ₁₇)×1500/4000 V ₂ " V ₁₇ +(V ₁₆ -V ₁₇)×1000/4000	r 3	500
2 ~1		01н	0	0	0	0	0	1	V1" V17+(V16-V17)×500/4000	r 1	500
	<u></u> V2 ′′	00н	0	0	0	0	0	0	Vo" V ₁₇	r o	500
1 0	Ч -									r total	20000
V17	- Vo''										_

Caution Between V₈ and V₉ terminal is not connected in the chip.



3. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format: 6 bits × 1 RGBs (3 dots) Input width: 18 bits (1-pixel data)

R,/L = H (Right shift)

	Output	S ₁	S ₂	S ₃	S ₄		S299/308	S300/309
I	Data	Doo to Do5	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₀₀ to D ₀₅	•••	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅

R,/L = L (Left shift)

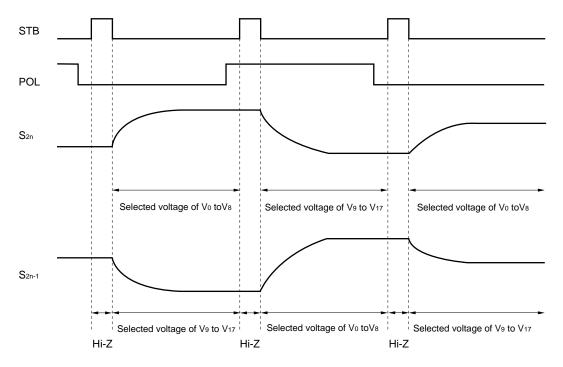
0	utput	S ₁	S ₂	S₃	S ₄	 S299/308	S300/309
	Data	Doo to Dos	D10 to D15	D20 to D25	Doo to Dos	 D10 to D15	D20 to D25

POL	S _{2n-1} Note	S _{2n} Note
Н	Vo to V8	V9 to V17
L	V9 to V17	Vo to V8

Note S_{2n-1} (Odd output), S_{2n} (Even output) $n = 1, 2, \dots, 155$ (Except S310)

4. RELATIONSHIP BETWEEN STB, POL, AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.





5. ELECTRICAL SPECIFICATION

Absolute Maximum Ratings (TA = 25°C, Vss1 = Vss2 = 0 V)

Parameter	Symbol	Rating	Unit
Logic Part Supply Voltage	V _{DD1}	-0.5 to +5.0	٧
Driver Part Supply Voltage	V _{DD2}	-0.5 to +10.0	V
Logic Part Input Voltage	VI1	-0.5 to V _{DD1} +0.5	V
Driver Part Input Voltage	V _{I2}	-0.5 to V _{DD2} +0.5	V
Logic Part Output Voltage	V ₀₁	-0.5 to V _{DD1} +0.5	V
Driver Part Output Voltage	Vo ₂	-0.5 to VDD2 +0.5	V
Output Voltage	Vo	-0.3 to V _{DD1/2} +0.3	V
Operating Temperature Range	TA	-10 to +75	°C
Storage Temperature Range	Tstg	−55 to +125	°C

Caution If the absolute maximum rating of even one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

Recommended Operating Range (T_A = -10 to +75°C, Vss₁ = Vss₂ = 0 V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Logic Part Supply Voltage	V _{DD1}	3.0	3.3	3.6	V
Driver Part Supply Voltage	V _{DD2}	8.0	8.5	9.0	V
High-Level Input Voltage	ViH	0.7 V _{DD1}		V _{DD1}	V
Low-Level Input Voltage	VIL	0		0.3 V _{DD1}	V
γ-Corrected Voltage	Vo to V17	Vss2		V _{DD2}	V
Driver Part Output Voltage	Vo	Vss2 + 0.1		V _{DD2} – 0.1	V
Maximum Clock Frequency	fmax.	40			MHz



Electrical Specifications (TA = -10 to +75°C, VDD1 = 3.3 V ± 0.3 V, VDD2 = 8.5 V ± 0.5 V, Vss1 = Vss2 = 0 V)

Parameter	Symbol	Condition		MIN.	TYP.	MAX.	Unit
Input Leak Current	l _L					±1.0	μΑ
High-Level Output Voltage	Vон	STHR (STHL), Ion = 0 mA		V _{DD1} – 0.1			V
Low-Level Output Voltage	Vol	STHR (STHL), IoL = 0 mA				0.1	V
γ -Corrected Supply Current	lγ	Vo to V4 = V5 to V9 =4.0V	V0, V4	126	252	504	μΑ
			V5, V9	-504	-252	-126	μΑ
Driver Output Current	Vvoн	$Vx = 7.0 \text{ V}, Vout = 6.5 \text{ V}^{Note}$				(T.B.D)	mA
	Vvol	$Vx = 1.0 \text{ V}, Vout = 1.5 \text{ V}^{Note}$		(T.B.D)			mA
Output Voltage Deviation	ΔVο	Input data			(±10)	±20	mV
Output swing difference deviation	ΔV_{P-P}	Input data			(±5)		mV
Output Voltage Range	Vo	Input data		0.1		V _{DD2} — 0.1	V
Logic Part Dynamic Current Consumption	I _{DD1}	V _{DD1} , with no load			(2.0)	(T.B.D)	mA
Driver Part Dynamic Current Consumption	I _{DD2}	V _{DD2} , with no load			(2.5)	(T.B.D)	mA

Note Vx refers to the output voltage of analog output pins S1 to S300/309.

Vouτ refers to the voltage applied to analog output pins S1 to S300/309.

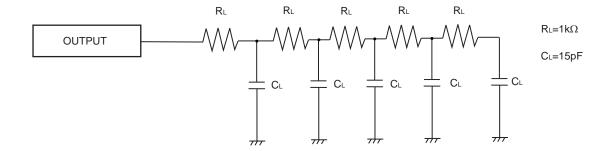
Cautions 1. The STB cycle is defined to be 20 μ s at fclk = 40 MHz.

- 2. The TYP. values refer to an all black or all white input pattern. The MAX. value refers to the measured values in the dot checkerboard input pattern.
- 3. Refers to the current consumption per driver when cascades are connected under the assumption of XGA single-sided mounting (8 units).

Switching Characteristics (TA = -10 to +75°C, VDD1 = 3.3 V ±0.3 V, VDD2 = 8.5 V ±0.5 V, VSS1 = VSS2 = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t PLH1	C _L = 10 pF		(10)	20	ns
Driver Output Delay Time 1	T _{PLH2}	$C_L = 75 \text{ pF}, R_L = 5 \text{ k}\Omega$		(2.5)	4	μs
	Трынз			(5)	7	μs
	T _{PHL2}			(2.5)	4	μs
	Трньз			(5)	7	μs
Input Capacitance 1	Cı1	STHR (STHL) excluded, T _A = 25°C		(5)	10	pF
Input Capacitance 2	C ₁₂	STHR (STHL), T _A = 25°C		(5)	10	pF



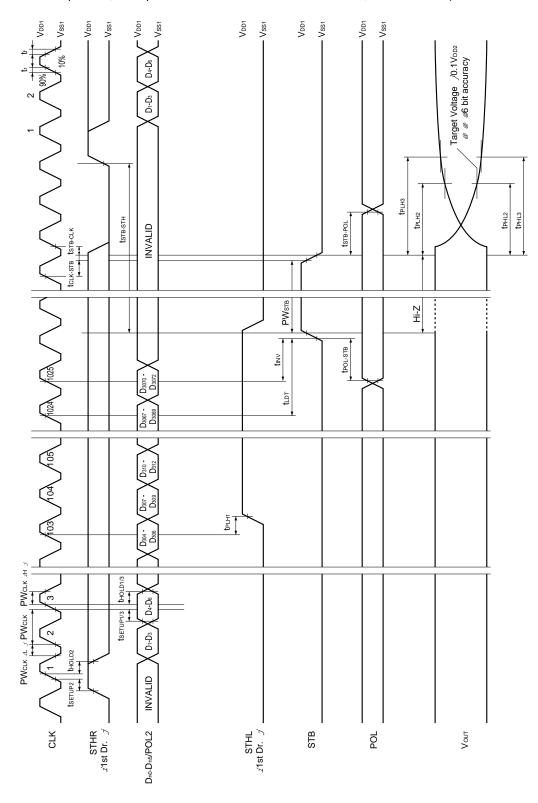


Timing Requirement (TA = -10 to +75°C, VDD1 = 3.3 V ± 0.3 V, Vss1 = Vss2 = 0 V, t_r = t_f = 8.0 ns)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Width	PWclk		25			ns
Clock Pulse High Period	PWclk(H)		4			ns
Clock Pulse Low Period	PWclk(L)		4			ns
Data Setup Time	tsetup1		4			ns
Data Hold Time	tHOLD1		0			ns
Start Pulse Setup Time	tsetup2		5			ns
Start Pulse Hold Time	tHOLD2		5			ns
POL2 Setup Time	tsetup3		4			ns
POL2 Hold Time	t HOLD3		0			ns
Start Pulse Low Period	t spl		6			ns
STB Pulse Width	PWstb		2			CLK
					4	μs
Data Invalid Period	tınv		1			CLK
Last Data Timing	t ldt		2			CLK
CLK-STB Time	tclk-stb	$CLK \uparrow \to STB \downarrow$	6			ns
STB-CLK Time	tstb-clk	$STB \downarrow \rightarrow CLK \downarrow$	6			ns
Time Between STB and Start Pulse	tsтв-sтн	$STB \downarrow \to STHR(STHL) \uparrow$	60			ns
POL-STB Time	tpol-stb	POL \uparrow or $\downarrow \rightarrow$ STB \uparrow	-5			ns
STB-POL Time	tstb-pol	$STB \downarrow \to POL \downarrow or \uparrow$	6			ns

6. SWITCHING CHARACTERISTICS WAVEFORM $(R_{*}/L = H)$

(Unless otherwise specified, the input level is defined to be VIH = 0.7 VDD1, VIL = 0.3 VDD1,)



7. RECOMMENDED SOLDERING CONDITIONS

The following conditions must be met for soldering conditions of the μ PD16638A.

For more details, refer to the Semiconductor Device Mounting Technology Manual (C10535E).

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

Type of Surface Mount Device

 μ PD16638AN- $\times\times$: TCP (TAB package)

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C: heating for 2 to 3 seconds: pressure 100 g (per solder)
	ACF (Adhesive Conductive Film)	Temporary bonding 70 to 100°C: pressure 3 to 8 kg/cm²: time 3 to 5 secs. Real bonding 165 to 180°C: pressure 25 to 45 kg/cm²: time 30 to 40 secs. (When using the anisotropy conductive film SUMIZAC1003 of Sumitomo Bakelite, Ltd.)

Caution To find out the detailed conditions for packaging the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more packaging methods at a time.

-NOTES FOR CMOS DEVICES-

(1) PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

(2) HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

Reference Documents

NEC Semiconductor Device Reliability / Quality Control System (C10983E)

Quality Grades to NEC's Semiconductor Devices (C11531E)

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

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NEC devices are classified into the following three quality grades:

"Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.

Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.

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